- Integrated Transient Voltage Suppression
- ESD Protection for Bus Terminals Exceeds: $\pm 30$ kV IEC 61000-4-2, Contact Discharge $\pm 15$ kV IEC 61000-4-2, Air-Gap Discharge $\pm 15$ kV EIA/JEDEC Human Body Model
- Circuit Damage Protection of 400-W Peak (Typical) Per IEC 61000-4-5
- Controlled Driver Output-Voltage Slew Rates Allow Longer Cable Stub Lengths
- 250-kbps in Electrically Noisy Environments
- Open-Circuit Fail-Safe Receiver Design
- 1/4 Unit Load Allows for 128 Devices Connected on Bus
- Thermal Shutdown Protection
- Power-Up/-Down Glitch Protection
- Each Transceiver Meets or Exceeds the Requirements of TIA/EIA-485 (RS-485) and ISO/IEC 8482:1993(E) Standards
- Low Disabled Supply Current $300 \mu \mathrm{~A}$ Max
- Pin Compatible With SN75176
- Applications:
- Industrial Networks
- Utility Meters
- Motor Control


## description

The SN75LBC184 and SN65LBC184 are differential data line transceivers in the trade-standard footprint of the SN75176 with built-in protection against high-energy noise transients. This feature provides a substantial increase in reliability for better immunity to noise transients coupled to the data cable over most existing devices. Use of these circuits provides a reliable low-cost direct-coupled (with no isolation transformer) data line interface without requiring any external components.
The SN75LBC184 and SN65LBC184 can withstand overvoltage transients of 400-W peak (typical). The conventional combination wave called out in IEC 61000-4-5 simulates the overvoltage transient and models a unidirectional surge caused by overvoltages from switching and secondary lightning transients.

SN65LBC184D (Marked as 6LB184)
SN75LBC184D (Marked as 7LB184)
SN65LBC184P (Marked as 65LBC184)
SN75LBC184P (Marked as 75LBC184)


## functional logic diagram (positive logic)



Figure 1. Surge Waveform - Combination Wave

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

## SN65LBC184, SN75LBC184

## DIFFERENTIAL TRANSCEIVER

WITH TRANSIENT VOLTAGE SUPPRESSION
SLLS236G - OCTOBER 1996 - REVISED MARCH 2007

## description (continued)

A biexponential function defined by separate rise and fall times for voltage and current simulates the combination wave. The standard $1.2 \mu \mathrm{~s} / 50 \mu \mathrm{~s}$ combination waveform is shown in Figure 1 and in the test description in Figure 15.

The device also includes additional desirable features for party-line data buses in electrically noisy environment applications including industrial process control. The differential-driver design incorporates slew-rate-controlled outputs sufficient to transmit data up to 250 kbps . Slew-rate control allows longer unterminated cable runs and longer stub lengths from the main backbone than possible with uncontrolled and faster voltage transitions. A unique receiver design provides a fail-safe output of a high level when the inputs are left floating (open circuit). The SN75LBC184 and SN65LBC184 receiver also includes a high input resistance equivalent to one-fourth unit load allowing connection of up to 128 similar devices on the bus.

The SN75LBC184 is characterized for operation from $0^{\circ} \mathrm{C}$ to $70^{\circ} \mathrm{C}$. The SN65LBC184 is characterized from $-40^{\circ} \mathrm{C}$ to $85^{\circ} \mathrm{C}$.

## schematic of inputs and outputs



DRIVER FUNCTION TABLE

| INPUT | ENABLE | OUTPUTS |  |
| :---: | :---: | :---: | :---: |
| D | DE | A | B |
| $H$ | $H$ | $H$ | L |
| L | $H$ | L | $H$ |
| $X$ | L | Z | Z |

$\mathrm{H}=$ high level, $\mathrm{L}=$ low level, ? = indeterminate, $X=$ irrelevant, $Z=$ high impedance (off)

RECEIVER FUNCTION TABLE

| DIFFERENTIAL INPUTS | ENABLE | OUTPUT |
| :---: | :---: | :---: |
| $\mathbf{A}-\mathbf{B}$ | $\overline{\mathbf{R E}}$ | $\mathbf{R}$ |
| $\mathrm{V}_{\mathrm{ID}} \geq 0.2 \mathrm{~V}$ | L | H |
| $-0.2 \mathrm{~V}<\mathrm{V}_{\mathrm{ID}}<0.2 \mathrm{~V}$ | L | $?$ |
| $\mathrm{~V}_{\mathrm{ID}} \leq-0.2 \mathrm{~V}$ | L | L |
| X | H | Z |
| Open | L | H |

$H$ = high level, $L=$ low level, ? = indeterminate, $X=$ irrelevant, $Z=$ high impedance (off)

AVAILABLE OPTIONS

| $\mathbf{T}_{\mathbf{A}}$ | PACKAGE |  |
| :---: | :---: | :---: |
|  | PLASTIC SMALL-OUTLINE $\dagger$ <br> (JEDEC MS-012) | PLASTIC DUAL-IN-LINE PACKAGE <br> (JEDEC MS-001) |
| $0^{\circ} \mathrm{C}$ to $70^{\circ} \mathrm{C}$ | SN75LBC184D | SN75LBC184P |
| $-40^{\circ} \mathrm{C}$ to $85^{\circ} \mathrm{C}$ | SN65LBC184D | SN65LBC184P |

$\dagger$ Add $R$ suffix for taped and reel.

## logic symbol $\dagger$


$\dagger$ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

# SN65LBC184, SN75LBC184 <br> DIFFERENTIAL TRANSCEIVER <br> WITH TRANSIENT VOLTAGE SUPPRESSION <br> SLLS236G - OCTOBER 1996 - REVISED MARCH 2007 

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted) $\dagger$

$$
\begin{aligned}
& \text { Supply voltage, } \mathrm{V}_{\mathrm{CC}} \text { (see Note 1) . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . . } 0.5 \mathrm{~V} \text { to } 7 \mathrm{~V} \\
& \dagger \text { Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and } \\
& \text { functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not } \\
& \text { implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. } \\
& \text { NOTES: 1. All voltage values, except differential input/output bus voltage, are with respect to network ground terminal } \\
& \text { 2. GND and bus terminal ESD protection is beyond readily available test equipment capabilities for IEC 61000-4-2, EIA/JEDEC test } \\
& \text { method A114-A and MIL-STD-883C method 3015. Ratings listed are limits of test equipment; device performance exceeds these } \\
& \text { limits. } \\
& \text { 3. Tested in accordance with JEDEC Standard 22, Test Method A114-A. } \\
& \text { 4. The driver shuts down at a junction temperature of approximately } 160^{\circ} \mathrm{C} \text {. To operate below this temperature, see the Dissipation } \\
& \text { Rating Table. }
\end{aligned}
$$

DISSIPATION RATING TABLE

| PACKAGE | $\mathbf{T}_{\mathbf{A}} \leq \mathbf{2 5}{ }^{\circ} \mathbf{C}$ <br> POWER RATING | DERATING FACTOR <br> ABOVE TA $^{2}=\mathbf{2 5}^{\circ} \mathbf{C}$ | $\mathbf{T}_{\mathbf{A}}=70^{\circ} \mathbf{C}$ <br> POWER RATING | $\mathbf{T}_{\mathbf{A}}=\mathbf{8 5}{ }^{\circ} \mathbf{C}$ <br> POWER RATING |
| :---: | :---: | :---: | :---: | :---: |
| D | 725 mW | $5.8 \mathrm{~mW} /{ }^{\circ} \mathrm{C}$ | 464 mW | 377 mW |
| P | 1150 mW | $9.2 \mathrm{~mW} /{ }^{\circ} \mathrm{C}$ | 736 mW | 598 mW |

## recommended operating conditions


$\ddagger$ The algebraic convention, in which the less-positive (more-negative) limit is designated minimum, is used in this data sheet.

## DRIVER SECTION

electrical characteristics over recommended operating conditions (unless otherwise noted)

|  | PARAMETER | ALTERNATE SYMBOLS | TEST CONDITIONS | MIN TYP ${ }^{\text {M }}$ MAX | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: |
| ICC | Supply current | NA | $\mathrm{DE}=\overline{\mathrm{RE}}=5 \mathrm{~V}$, No Load | $12 \quad 25$ | mA |
|  |  |  | $\mathrm{DE}=0 \mathrm{~V}$, $\overline{\mathrm{RE}}=5 \mathrm{~V}$, <br> No Load  | 175300 | $\mu \mathrm{A}$ |
| IIH | High-level input current (D, DE, $\overline{\mathrm{RE}}$ ) | NA | $\mathrm{V}_{\mathrm{I}}=2.4 \mathrm{~V}$ | 50 | $\mu \mathrm{A}$ |
| IIL | Low-level input current ( $\mathrm{D}, \mathrm{DE}, \overline{\mathrm{RE}}$ ) | NA | $\mathrm{V}_{\mathrm{I}}=0.4 \mathrm{~V}$ | -50 | $\mu \mathrm{A}$ |
| Ios | Short-circuit output current (see Note 5) | NA | $\mathrm{V}_{\mathrm{O}}=-7 \mathrm{~V}$ | -250 -120 | mA |
|  |  |  | $\mathrm{V}_{\mathrm{O}}=\mathrm{V}_{\mathrm{CC}}$ | 250 |  |
|  |  |  | $\mathrm{V}_{\mathrm{O}}=12 \mathrm{~V}$ | 250 |  |
| loz | High-impedance output current | NA |  | See Receiver II | mA |
| $\mathrm{V}_{\mathrm{O}}$ | Output voltage | $\mathrm{V}_{\text {oa }}, \mathrm{V}_{\text {ob }}$ | $\mathrm{O}=0$ | $0 \quad \mathrm{~V}_{\mathrm{CC}}$ | V |
| VOC(PP) | Peak-to-peak change in commonmode output voltage during state transitions | NA | See Figures 5 and 6 | 0.8 | V |
| VOC | Common-mode output voltage | \| $\mathrm{V}_{\text {os }} \mid$ | See Figure 4 | 1 3 | V |
| $\mid \triangle \mathrm{V}_{\text {OC(SS }}{ }^{\text {\| }}$ | Magnitude of change, commonmode steady-state output voltage | \| $\mathrm{V}_{\text {OS }}-\overline{\mathrm{V}}_{\text {OS }} \mid$ | See Figure 5 | 0.1 | V |
| \|VOD ${ }^{\text {I }}$ | Magnitude of differential output voltage $\left\|\mathrm{V}_{\mathrm{A}}-\mathrm{V}_{\mathrm{B}}\right\|$ | $\mathrm{V}_{0}$ | $\mathrm{I}=0$ | 1.56 | V |
|  |  |  | $\mathrm{R}_{\mathrm{L}}=54 \Omega, \quad$ See Figure 4 | 1.5 | V |
| $\Delta \mid \mathrm{V}_{\text {OD }}$ | Change in differential voltage magnitude between logic states | $\left\|\left\|\mathrm{V}_{\mathrm{t}}\right\|-\left\|\overline{\mathrm{V}}_{\mathrm{t}}\right\|\right\|$ | $R_{L}=54 \Omega$ | 0.1 | V |

$\dagger$ All typical values are measured with $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ and $\mathrm{V}_{\mathrm{CC}}=5 \mathrm{~V}$.
NOTE 5: This parameter is measured with only one output being driven at a time.
switching characteristics over recommended operating conditions (unless otherwise noted)

|  | PARAMETER | TEST CONDITIONS |  | MIN | TYP | MAX | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{t}_{\mathrm{d}(\mathrm{DH})}$ | Differential output delay time, low-to-high-level output | $\begin{array}{ll} R_{\mathrm{L}}=54 \Omega, & C_{\mathrm{L}}=50 \mathrm{pF}, \\ \text { See Figure } 5 & \end{array}$ |  |  |  | 1.3 | $\mu \mathrm{s}$ |
| $t_{\text {d }}(\mathrm{DL})$ | Differential-output delay time, high-to-low-level output |  |  |  |  | 1.3 | $\mu \mathrm{S}$ |
| tplH | Propagation delay time, low-to-high-level output |  |  |  | 0.5 | 1.3 | $\mu \mathrm{s}$ |
| tPHL | Propagation delay time, high-to-low-level output |  |  |  | 0.5 | 1.3 | $\mu \mathrm{s}$ |
| $\mathrm{t}_{\text {sk }}(\mathrm{p})$ | Pulse skew (\| $\mathrm{t}_{\mathrm{d}}(\mathrm{DH})-\mathrm{t}_{\mathrm{d}(\mathrm{DL}} \mid$ ) |  |  |  | 75 | 150 | ns |
| $\mathrm{tr}_{\mathrm{r}}$ | Rise time, single ended |  |  | 0.25 |  | 1.2 | $\mu \mathrm{s}$ |
| $\mathrm{tf}_{\text {f }}$ | Fall time, single ended |  |  | 0.25 |  | 1.2 | $\mu \mathrm{s}$ |
| tPZH | Output enable time to high level | $\mathrm{R}_{\mathrm{L}}=110 \Omega$, | See Figure 2 |  |  | 3.5 | $\mu \mathrm{s}$ |
| tPZL | Output enable time to low level | $\mathrm{R}_{\mathrm{L}}=110 \Omega$, | See Figure 3 |  |  | 3.5 | $\mu \mathrm{s}$ |
| tPHZ | Output disable time from high level | $\mathrm{R}_{\mathrm{L}}=110 \Omega$, | See Figure 2 |  |  | 2 | $\mu \mathrm{s}$ |
| tplZ | Output disable time from low level | $\mathrm{R}_{\mathrm{L}}=110 \Omega$, | See Figure 3 |  |  | 2 | $\mu \mathrm{s}$ |

## RECEIVER SECTION

electrical characteristics over recommended operating conditions (unless otherwise noted)

|  | PARAMETER | TEST CONDITIONS |  |  | MIN | TYP† | MAX | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| ${ }^{\text {ICC }}$ | Supply current (total package) | $\mathrm{DE}=\overline{\mathrm{RE}}=0 \mathrm{~V}$, | No Load |  |  |  | 3.9 | mA |
|  |  | $\begin{array}{\|l\|} \hline \overline{\mathrm{RE}}=5 \mathrm{~V}, \\ \text { No Load } \end{array}$ | $\mathrm{DE}=0 \mathrm{~V}$, |  |  |  | 300 | $\mu \mathrm{A}$ |
| 1 | Input current | Other input $=0 \mathrm{~V}$ | $\mathrm{V}_{\mathrm{I}}=12 \mathrm{~V}$ |  |  |  | 250 | $\mu \mathrm{A}$ |
|  |  |  | $\mathrm{V}_{\mathrm{I}}=12 \mathrm{~V}$, | $\mathrm{V}_{\mathrm{CC}}=0$ |  |  | 250 |  |
|  |  |  | $\mathrm{V}_{\mathrm{I}}=-7 \mathrm{~V}$ |  | -200 |  |  |  |
|  |  |  | $\mathrm{V}_{\mathrm{I}}=-7 \mathrm{~V}$, | $\mathrm{V}_{\mathrm{CC}}=0$ | -200 |  |  |  |
| loz | High-impedance-state output current | $\mathrm{V}_{\mathrm{O}}=0.4 \mathrm{~V}$ to 2.4 V |  |  |  |  | $\pm 100$ | $\mu \mathrm{A}$ |
| $\mathrm{V}_{\text {hys }}$ | Input hysteresis voltage |  |  |  |  | 70 |  | mV |
| $\mathrm{V}_{\text {IT }+}$ | Positive-going input threshold voltage |  |  |  |  |  | 200 | mV |
| $\mathrm{V}_{\text {IT- }}$ | Negative-going input threshold voltage |  |  |  | -200 |  |  | mV |
| $\mathrm{V}_{\mathrm{OH}}$ | High-level output voltage | $\mathrm{IOH}=-8 \mathrm{~mA}$ | Figure 7 |  | 2.8 |  |  | V |
| $\mathrm{V}_{\text {OL }}$ | Low-level output voltage | $\mathrm{I} \mathrm{OL}=4 \mathrm{~mA}$ | Figure 7 |  |  |  | 0.4 | V |

$\dagger$ All typical values are at $\mathrm{V}_{\mathrm{CC}}=5 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$.
switching characteristics over recommended operating conditions (unless otherwise noted)

| PARAMETER |  | TEST CONDITIONS |  | MIN | TYP | MAX | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| tPLH | Propagation delay time, low-to-high-level output | $C_{L}=50 \mathrm{pF}$, | See Figure 7 |  |  | 150 | ns |
| tPHL | Propagation delay time, high-to-low-level output |  |  |  |  | 150 | ns |
| $\mathrm{t}_{\text {sk }}(\mathrm{p})$ | Pulse skew (\|tpHL - tpLH|) |  |  |  |  | 50 | ns |
| $\mathrm{tr}_{\mathrm{r}}$ | Rise time, single ended | See Figure 7 |  |  | 20 |  | ns |
| $\mathrm{tf}^{\text {f }}$ | Fall time, single ended |  |  |  | 20 |  | ns |
| tPZH | Output enable time to high level | See Figure 8 |  |  |  | 100 | ns |
| tPZL | Output enable time to low level |  |  |  |  | 100 | ns |
| tPHZ | Output disable time from high level |  |  |  |  | 100 | ns |
| tplZ | Output disable time from low level |  |  |  |  | 100 | ns |

## PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT
VOLTAGE WAVEFORMS
NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR $=1.25 \mathrm{kHz}, 50 \%$ duty cycle, $\mathrm{t}_{\mathrm{r}} \leq 10 \mathrm{~ns}$, $\mathrm{t}_{\mathrm{f}} \leq 10 \mathrm{~ns}, \mathrm{Z}_{\mathrm{O}}=50 \Omega$.
B. $\mathrm{C}_{\mathrm{L}}$ includes probe and jig capacitance.

Figure 2. Driver t $_{\text {PZH }}$ and tPHZ $^{\text {Test Circuit and Voltage Waveforms }}$


Figure 3. Driver $t_{\text {PZL }}$ and tpLz Test Circuit and Voltage Waveforms


NOTES: A. Resistance values are in ohms and are $1 \%$ tolerance.
B. $C_{L}$ includes probe and jig capacitance.

Figure 4. Driver Test Circuit, Voltage, and Current Definitions

PARAMETER MEASUREMENT INFORMATION


Figure 5. Driver Timing, Voltage and Current Waveforms

## PARAMETER MEASUREMENT INFORMATION



Inputs


VOC(PP)
NOTES: A. Resistance values are in ohms and are $1 \%$ tolerance.
B. $C_{L}$ includes probe and jig capacitance ( $\pm 10 \%$ ).

Figure 6. Driver $\mathrm{V}_{\mathrm{OC}(\mathrm{PP})}$ Test Circuit and Waveforms


NOTE A: This value includes probe and jig capacitance ( $\pm 10 \%$ ).
Figure 7. Receiver $\mathrm{t}_{\text {PLH }}$ and $\mathrm{t}_{\text {PHL }}$ Test Circuit and Voltage Waveforms

## PARAMETER MEASUREMENT INFORMATION



A


NOTE A: This value includes probe and jig capacitance ( $\pm 10 \%$ ).
Figure 8. Receiver $t_{\text {PZL }}$, t $_{\text {PLZ }}$, tPZH , and $t_{\text {PHZ }}$ Test Circuit and Voltage Waveforms

## TYPICAL CHARACTERISTICS

DRIVER DIFFERENTIAL OUTPUT VOLTAGE
VS
FREE-AIR TEMPERATURE


Figure 9

DRIVER TRANSITION TIME
vs
FREE-AIR TEMPERATURE


Figure 11

DRIVER PROPAGATION DELAY TIME vs
FREE-AIR TEMPERATURE


Figure 10

DIFFERENTIAL OUTPUT VOLTAGE vs OUTPUT CURRENT


Figure 12

## TYPICAL CHARACTERISTICS



Figure 13

APPLICATION INFORMATION


NOTE A: The line should be terminated at both ends in its characteristic impedance $\left(R_{T}=Z_{O}\right)$. Stub lengths off the main line should be kept as short as possible.

Figure 14. Typical Application Circuit

## APPLICATION INFORMATION

## 'LBC184 test description

The 'LBC184 is tested against the IEC 61000-4-5 recommended transient identified as the combination wave. The combination wave provides a 1.2-/50- $\mu \mathrm{s}$ open-circuit voltage waveform and a $8-/ 20-\mu \mathrm{s}$ short-circuit current waveform shown in Figure 15. The testing is performed with a combination/hybrid pulse generator with an effective output impedance of $2 \Omega$. The setup for the overvoltage stress is shown in Figure 16 with all testing performed with power applied to the 'LBC184 circuit.

## NOTE

High voltage transient testing is done on a sampling basis.



Figure 15. Short-Circuit Current Waveforms
The 'LBC184 is tested and evaluated for both maximum (single pulse) as well as life test (multiple pulse) capabilities. The 'LBC184 is evaluated against transients of both positive and negative polarity and all testing is performed with the worst-case transient polarity. Transient pulses are applied to the bus pins (A \& B) across ground as shown in Figure 16.


Figure 16. Overvoltage-Stress Test Circuit
An example waveform as seen by the 'LBC184 is shown in Figure 17. The bottom trace is current, the middle trace shows the clamping voltage of the device and the top trace is power as calculated from the voltage and current waveforms. This example shows a peak clamping voltage of 33.6 V and peak current of 16 A , thus yielding an absorbed peak power of 538 W .

## NOTE

A circuit reset may be required to ensure normal data communications following a transient noise pulse of greater than 250 W peak.

## APPLICATION INFORMATION



Figure 17. Typical Surge Waveform Measured At Terminals 5 and 7
www.ti.com

## PACKAGING INFORMATION

| Orderable Device | Status ${ }^{(1)}$ | Package <br> Type | Package <br> Drawing | Pins Package <br> Qty | Eco Plan ${ }^{(2)}$ | Lead/Ball Finish | MSL Peak Temp ${ }^{(3)}$ |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| SN65LBC184D | ACTIVE | SOIC | D | 8 | 75 |  <br> no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN65LBC184DG4 | ACTIVE | SOIC | D | 8 | 75 |  <br> no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN65LBC184DR | ACTIVE | SOIC | D | 8 | 2500 |  <br> no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN65LBC184DRG4 | ACTIVE | SOIC | D | 8 | 2500 |  <br> no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN65LBC184P | ACTIVE | PDIP | P | 8 | 50 | Pb-Free <br> (RoHS) | CU NIPDAU | N/A for Pkg Type |
| SN65LBC184PE4 | ACTIVE | PDIP | P | 8 | 50 | Pb-Free <br> (RoHS) | CU NIPDAU | N/A for Pkg Type |
| SN75LBC184D | ACTIVE | SOIC | D | 8 | 75 |  <br> no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN75LBC184DG4 | ACTIVE | SOIC | D | 8 | 75 |  <br> no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN75LBC184DR | ACTIVE | SOIC | D | 8 | 2500 |  <br> no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN75LBC184DRG4 | ACTIVE | SOIC | D | 8 | 2500 |  <br> no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN75LBC184P | ACTIVE | PDIP | P | 8 | 50 | Pb-Free <br> (RoHS) | CU NIPDAU | N/A for Pkg Type |
| SN75LBC184PE4 | ACTIVE | PDIP | P | 8 | 50 | Pb-Free <br> (RoHS) | CU NIPDAU | N/A for Pkg Type |

${ }^{(1)}$ The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.
${ }^{(2)}$ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS \& no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The $\mathrm{Pb}-\mathrm{Free} / \mathrm{Green}$ conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed $0.1 \%$ by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb -Free products are suitable for use in specified lead-free processes.
Pb -Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb -Free (RoHS compatible) as defined above.
Green (RoHS \& no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants ( Br or Sb do not exceed $0.1 \%$ by weight in homogeneous material)
${ }^{(3)}$ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE OPTION ADDENDUM INSTRUMENTS

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

## TAPE AND REEL INFORMATION


*All dimensions are nominal

| Device | Package <br> Type | Package <br> Drawing | Pins | SPQ | Reel <br> Diameter <br> $(\mathbf{m m})$ | Reel <br> Width <br> W1 $(\mathbf{m m})$ | A0 $(\mathbf{m m})$ | B0 $(\mathbf{m m})$ | K0 (mm) | P1 <br> $(\mathbf{m m})$ | W <br> $(\mathbf{m m})$ | Pin1 <br> Quadrant |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| SN65LBC184DR | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |
| SN65LBC184DR | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |
| SN75LBC184DR | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |
| SN75LBC184DR | SOIC | D | 8 | 2500 | 330.0 | 12.4 | 6.4 | 5.2 | 2.1 | 8.0 | 12.0 | Q1 |


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| SN65LBC184DR | SOIC | D | 8 | 2500 | 346.0 | 346.0 | 29.0 |
| SN65LBC184DR | SOIC | D | 8 | 2500 | 340.5 | 338.1 | 20.6 |
| SN75LBC184DR | SOIC | D | 8 | 2500 | 346.0 | 346.0 | 29.0 |
| SN75LBC184DR | SOIC | D | 8 | 2500 | 340.5 | 338.1 | 20.6 |

D (R-PDSO-G8)

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.

Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed $.006(0,15)$ per end.
D Body width does not include interlead flash. Interlead flash shall not exceed $.017(0,43)$ per side.
E. Reference JEDEC MS-012 variation AA.


NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS-001

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